GAP PAD Dispensable

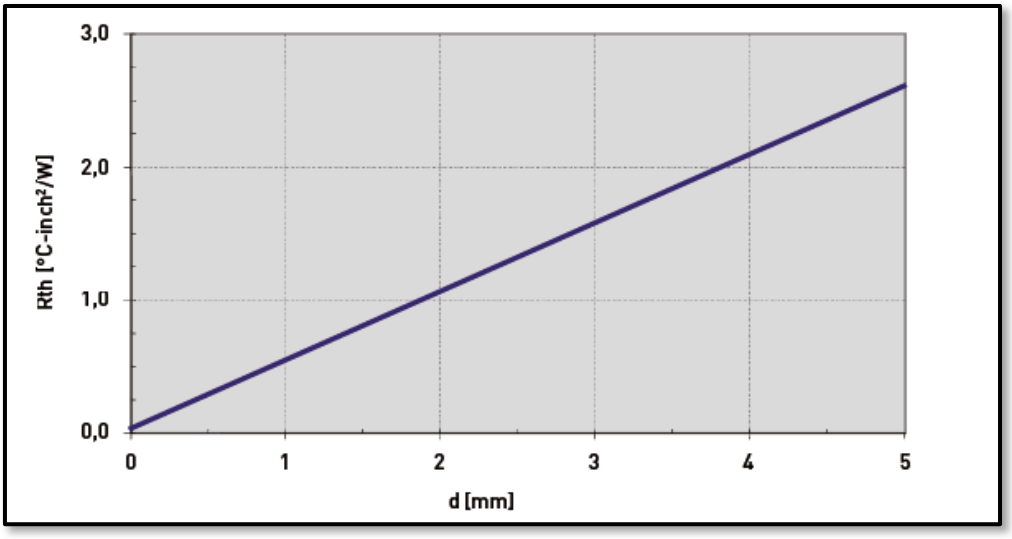
FT_TDG_030_T_30

Our Thermal Foams also called TDG is a low volatility LV silicone space filler dispensable in 2 parts that is filled with thermally conductive fillers. After hardening under heat the system remains elastic. The TDG_030_T is characterized by very good dielectric and mechanical properties and is suitable to compensate for extreme tolerances and spaces in non-planar systems. Indeed, this one is a GOOD thermal conductor of 3W/mK, with a good thermal resistance thus facilitating the heat transfer and which also has an excellent electrical insulation. All our TDG are UL 94 V0 certified.

Application areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR ll Module, etc.

Technical characteristics

Features	Unit	TDG_030_T	
Thickness	mm	A Part	B Part
Density	g/cm^3	2.75	
Color	-	Blue	White
Hardness	Shore 00	55	
Packaging	//	Cartridge 2x25/100/200/600ml // Seal 2x25/35 Kg	
Viscosity	PAS	290	260
Hardening temsp	25 /100°C	< 15h / 15/30min	< 15h / 15/30min
Outgassing	TML	0.07	0.07
Thermal Conductivity	W/mK	3.0	
Temperature	°C	-60 to 180	
Breakdown voltage	kV/mm	> 10	
Volume resistance	0hm - cm	1.0x 10^{10}	



Results obtained under laboratory conditions and should be considered as a guide only. AB2E has no control over its customers' hardware and many other factors, it is the user's responsibility to perform their own tests to ensure that the product meets their needs.